PRODUCT BRIEF

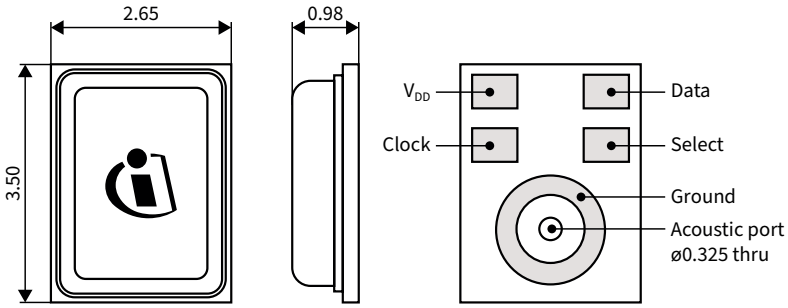
# IM66D132H

## Low power digital PDM XENSIV™ MEMS microphone

### Product overview

| Key parameters | Normal mode |
|---|---|
| **Enviromental robustness** | IP57 |
| **Sensitivity @ 1 kHz, 94 dBSPL** | -37/-21 ± 1 dBFS (HPM/LPM) |
| **Signal-to-noise ratio (SNR)** | 66 dB(A) |
| **Current consumption** | 580 µA |
| **Acoustic overload point (1/10% THD)** | 128 dBSPL/132 dBSPL |
| **Low frequency roll-off (LFRO)** | 20 Hz |
| **Supply voltage** | 1.62 to 3.60 V |
| **Interface** | Digital PDM |
| **Port location** | Bottom port |
| **Package dimension** | 3.5 x 2.65 x 0.98 mm |

### Package information




Top view Side view Bottom view

All dimensions in mm

### Key features

- Low 580 µA current consumption in always on mode
- Component level IP57 water and dust resistant
- 66 dB(A) Signal-to-noise ratio
- Acoustic overload point (AOP) of 132 dBSPL
- Tight sensitivity (-37/-21 ± 1 dB) tolerance
- 20 Hz low frequency roll-off

### Key benefits

- Battery saving without compromising in acoustic performance
- Clear audio signals even for high sound pressure levels
- Highest precision of audio beams and algorithms

### Typical applications

- Active Noise Cancellation (ANC): headphones and earphones
- Smartphones and mobile devices
- Hearing enhancement devices
- Voice User Interface (VUI): e.g. smart speaker, home automation, and IOT devices
- Power constrained applications

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